- Member of the Texas Instruments Widebus™ Family
- Load Clock and Unload Clock Can Be Asynchronous or Coincident
- 64 Words by 18 Bits
- Low-Power Advanced CMOS Technology
- Full, Empty, and Half-Full Flags
- Programmable Almost-Full/Almost-Empty Flag
- Fast Access Times of 15 ns With a 50-pF Load and All Data Outputs Switching Simultaneously
- Data Rates up to 50 MHz
- 3-State Outputs
- Pin-to-Pin Compatible With SN74ACT7804 and SN74ACT7806
- Packaged in Shrink Small-Outline 300-mil Package Using 25-mil Center-to-Center Spacing

DL PACKAGE
(TOP VIEW)

$\overline{\text{RESET}}$	1	56	$\overline{\text{OE}}$
D17	2	55	Q17
D16	3	54	Q16
D15	4	53	Q15
D14	5	52	GND
D13	6	51	Q14
D12	7	50	V_{CC}
D11	8	49	Q13
D10	9	48	Q12
V_{CC}	10	47	Q11
D9	11	46	Q10
D8	12	45	Q9
GND	13	44	GND
D7	14	43	Q8
D6	15	42	Q7
D5	16	41	Q6
D4	17	40	Q5
D3	18	39	V_{CC}
D2	19	38	Q4
D1	20	37	Q3
D0	21	36	Q2
HF	22	35	GND
$\overline{\text{PEN}}$	23	34	Q1
AF/AE	24	33	Q0
LDCK	25	32	UNCK
NC	26	31	NC
NC	27	30	NC
$\overline{\text{FULL}}$	28	29	$\overline{\text{EMPTY}}$

description

A FIFO memory is a storage device that allows data to be written into and read from its array at independent data rates. The SN74ACT7814 is a 64-word by 18-bit FIFO for high speed and fast access times. It processes data at rates up to 50 MHz and access times of 15 ns in a bit-parallel format.

Data is written into memory on a low-to-high transition at the load clock (LDCK) input and is read out on a low-to-high transition at the unload clock (UNCK) input. The memory is full when the number of words clocked in exceeds the number of words clocked out by 64. When the memory is full, LDCK signals have no effect on the data residing in memory. When the memory is empty, UNCK signals have no effect.

Status of the FIFO memory is monitored by the full ($\overline{\text{FULL}}$), empty ($\overline{\text{EMPTY}}$), half-full (HF), and almost-full/almost-empty (AF/AE) flags. The $\overline{\text{FULL}}$ output is low when the memory is full and high when the memory is not full. The $\overline{\text{EMPTY}}$ output is low when the memory is empty and high when it is not empty. The HF output is high when the FIFO contains 32 or more words and is low when it contains 31 or fewer words. The AF/AE status flag is a programmable flag. The first one or two low-to-high transitions of LDCK after reset are used to program the almost-empty offset value (X) and the almost-full offset value (Y) if program enable ($\overline{\text{PEN}}$) is low. The AF/AE flag is high when the FIFO contains X or fewer words or (64 – Y) or more words. The AF/AE flag is low when the FIFO contains between (X + 1) and (63 – Y) words.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus is a trademark of Texas Instruments Incorporated.

TEXAS INSTRUMENTS

POST OFFICE BOX 655303 ● DALLAS, TEXAS 75265

SN74ACT7814
# 64 × 18 STROBED FIRST-IN, FIRST-OUT MEMORY

SCAS209C – APRIL 1992 – REVISED APRIL 1998

description (continued)

A low level on the reset ($\overline{\text{RESET}}$) input resets the internal stack pointers and sets $\overline{\text{FULL}}$ high, HF low, and $\overline{\text{EMPTY}}$ low. The Q outputs are not reset to any specific logic level. The FIFO must be reset upon power up. The first word loaded into empty memory causes $\overline{\text{EMPTY}}$ to go high and the data to appear on the Q outputs. It is important to note that the first word does not have to be unloaded. The data outputs are noninverting with respect to the data inputs and are in the high-impedance state when the output-enable ($\overline{\text{OE}}$) input is high.
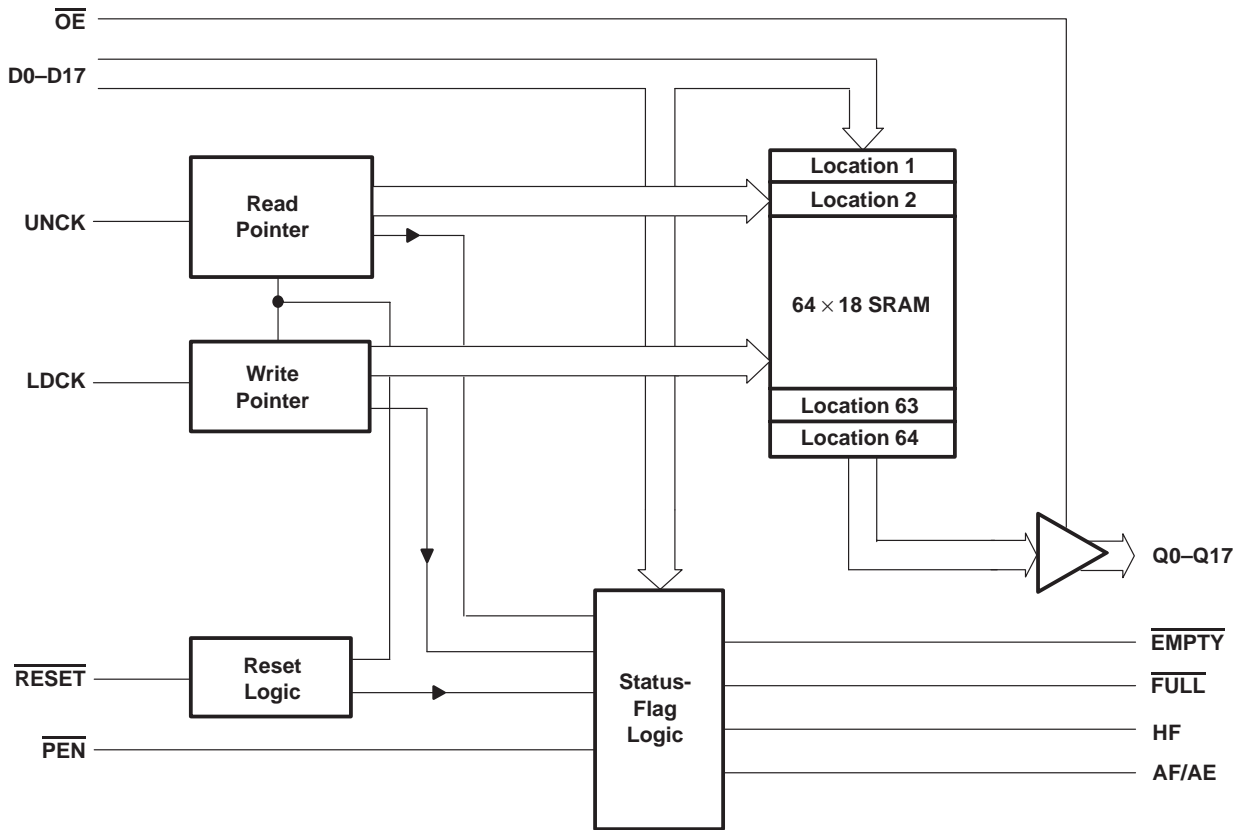
The SN74ACT7814 is characterized for operation from 0°C to 70°C.

logic symbol†
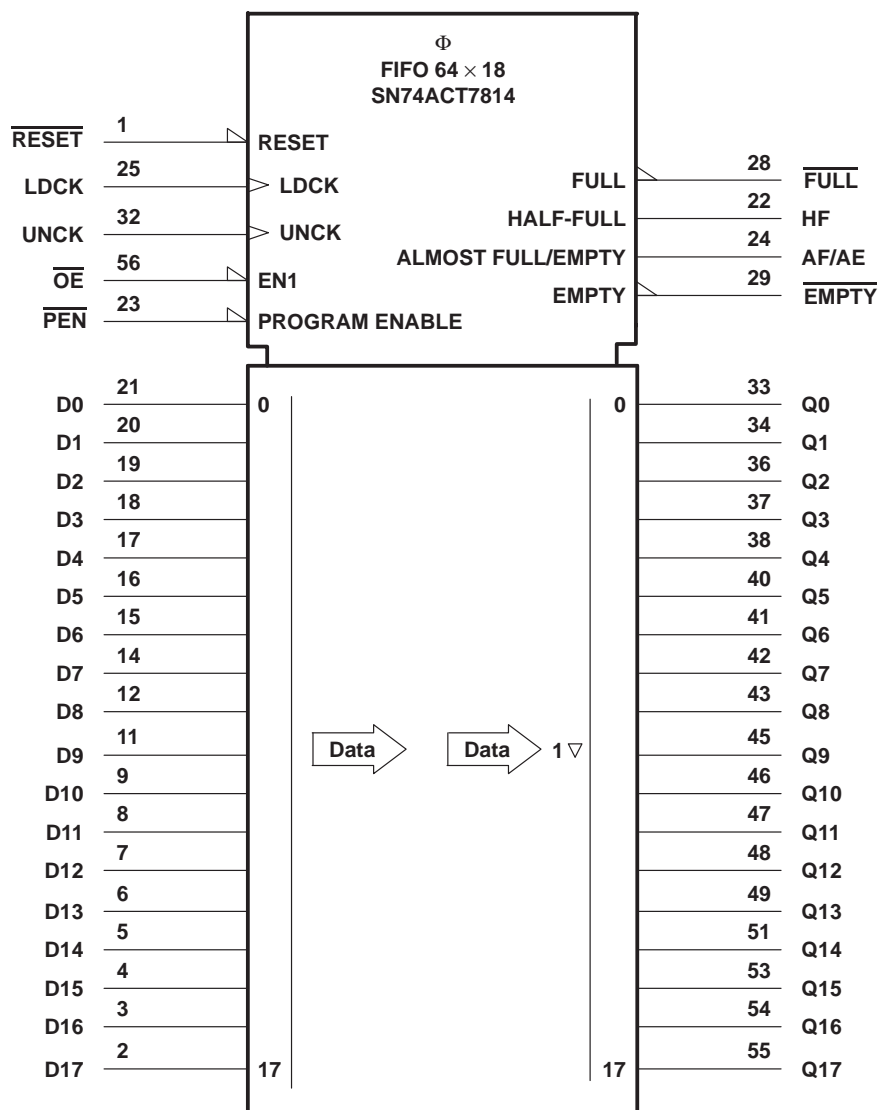
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

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functional block diagram

Terminal Functions

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
AF/AE	24	O	Almost-full/almost-empty flag. Depth-offset values can be programmed for AF/AE, or the default value of 8 can be used for both the almost-empty offset (X) and the almost-full offset (Y). AF/AE is high when memory contains X or fewer words or (64 – Y) or more words. AF/AE is high after reset.
D0–D17	2–9, 11–12, 14–21	I	18-bit data input port
$\overline{\text{EMPTY}}$	29	O	Empty flag. $\overline{\text{EMPTY}}$ is high when the FIFO memory is not empty; $\overline{\text{EMPTY}}$ is low when the FIFO memory is empty or upon assertion of $\overline{\text{RESET}}$.
$\overline{\text{FULL}}$	28	O	Full flag. $\overline{\text{FULL}}$ is high when the FIFO memory is not full or upon assertion of $\overline{\text{RESET}}$; $\overline{\text{FULL}}$ is low when the FIFO memory is full.
HF	22	O	Half-full flag. HF is high when the FIFO memory contains 32 or more words. HF is low after reset.
LDCK	25	I	Load clock. Data is written to the FIFO on the rising edge of LDCK when $\overline{\text{FULL}}$ is high.
$\overline{\text{OE}}$	56	I	Output enable. When $\overline{\text{OE}}$ is high, the data outputs are in the high-impedance state.
$\overline{\text{PEN}}$	23	I	Program enable. After reset and before the first word is written to the FIFO, the binary value on D0–D4 is latched as an AF/AE offset value when $\overline{\text{PEN}}$ is low and WRTCLK is high.
Q0–Q17	33–34, 36–38, 40–43, 45–49, 51, 53–55	O	18-bit data output port
$\overline{\text{RESET}}$	1	I	Reset. A low level on $\overline{\text{RESET}}$ resets the FIFO and drives $\overline{\text{FULL}}$ high and HF and $\overline{\text{EMPTY}}$ low.
UNCK	32	I	Unload clock. Data is read from the FIFO on the rising edge of UNCK when $\overline{\text{EMPTY}}$ is high.

offset values for AF/AE

The AF/AE flag has two programmable limits: the almost-empty offset value (X) and the almost-full offset value (Y). They can be programmed after the FIFO is reset and before the first word is written to memory. The AF/AE flag is high when the FIFO contains X or fewer words or $(64 - Y)$ or more words.

To program the offset values, $\overline{PEN}$ can be brought low after reset only when LDCK is low. On the following low-to-high transition of LDCK, the binary value on D0–D4 is stored as the almost-empty offset value (X) and the almost-full offset value (Y). Holding $\overline{PEN}$ low for another low-to-high transition of LDCK reprograms Y to the binary value on D0–D4 at the time of the second LDCK low-to-high transition. Writes to the FIFO memory are disabled while the offsets are programmed. A maximum value of 31 can be programmed for either X or Y (see Figure 1). To use the default values of X = Y = 8, $\overline{PEN}$ must be held high.
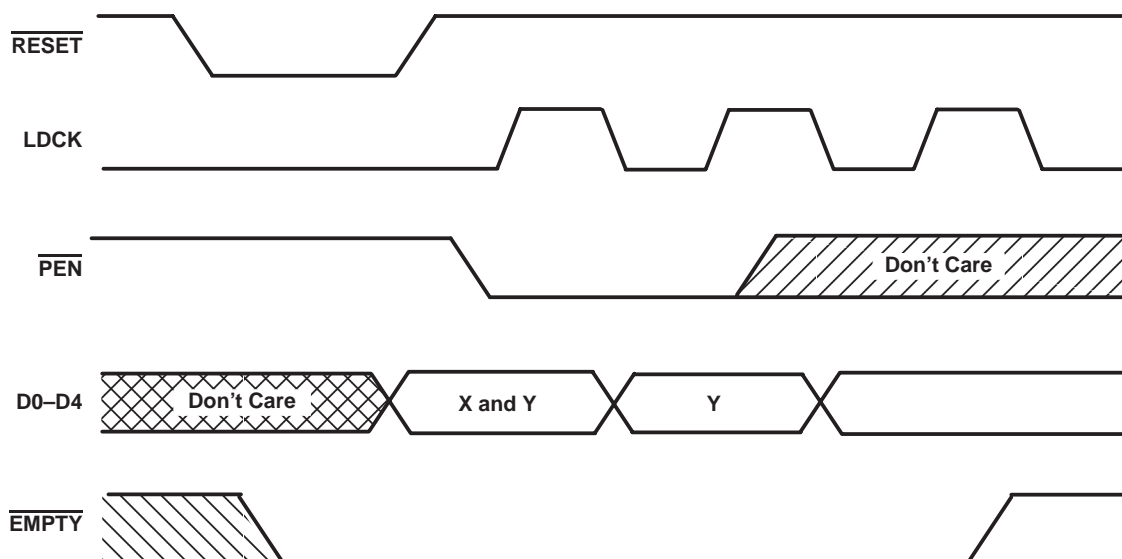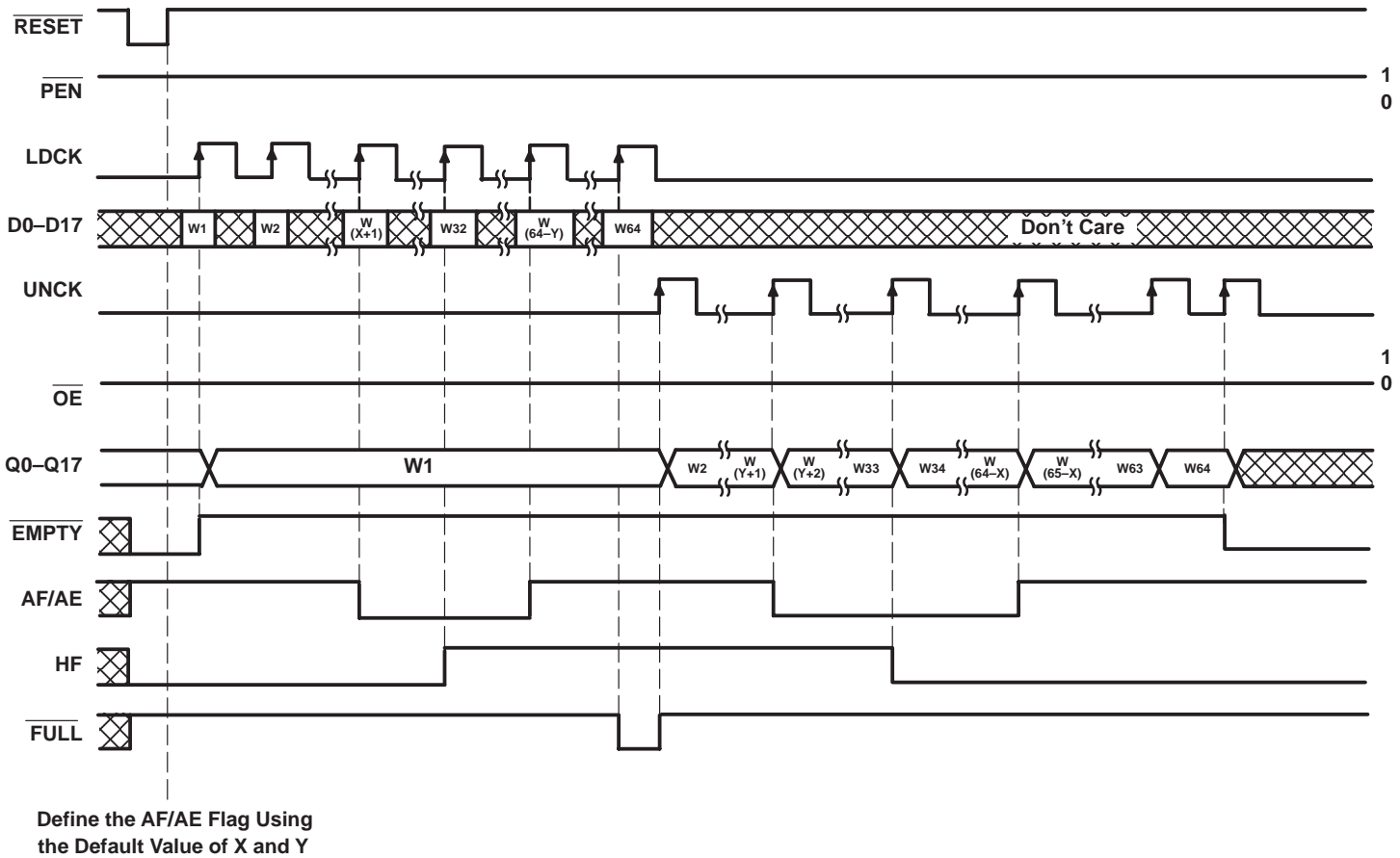

Figure 1. Programming X and Y Separately

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Figure 2. Write, Read, and Flag Timing Reference

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} .... –0.5 V to 7 V
Input voltage range, V_I .... –0.5 V to 7 V
Voltage range applied to a disabled 3-state output .... –0.5 V to 5.5 V
Package thermal impedance, θ_{JA} (see Note 1) .... 74°C/W
Storage temperature range, T_{stg} .... –65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTE 1:   The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions

			'ACT7814-20		'ACT7814-25		'ACT7814-40		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8		0.8	V
I_{OH}	High-level output current	Q outputs, flags		–8		–8		–8	mA
I_{OL}	Low-level output current	Q outputs		16		16		16	mA
		Flags		8		8		8	
T_A	Operating free-air temperature		0	70	0	70	0	70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP[‡]	MAX	UNIT
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –8 mA	2.4			V
V_{OL}	Flags	V_{CC} = 4.5 V,	I_{OL} = 8 mA			0.5	V
	Q outputs	V_{CC} = 4.5 V,	I_{OL} = 16 mA			0.5	
I_I		V_{CC} = 5.5 V,	V_I =V_{CC} or 0			±5	µA
I_{OZ}		V_{CC} = 5.5 V,	V_O =V_{CC} or 0			±5	µA
I_{CC}		V_I = V_{CC} – 0.2 V or 0				400	µA
ΔI_{CC}[§]		V_{CC} = 5.5 V,	One input at 3.4 V, Other inputs at V_{CC} or GND			1	mA
C_i		V_I = 0,	f = 1 MHz			4	pF
C_o		V_O = 0,	f = 1 MHz			8	pF

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.
[§] This is the supply current for each input that is at one of the specified TTL voltage levels rather 0 V or V_{CC}.

timing requirements over recommended operating conditions (see Figures 1 through 3)

			'ACT7814-20		'ACT7814-25		'ACT7814-40		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency			50		40		25	MHz
t_w	Pulse duration	LDCK high or low	7		8		12		ns
		UNCK high or low	7		8		12		
		$\overline{PEN}$ low	7		8		12		
		$\overline{RESET}$ low	10		10		12		
t_{su}	Setup time	D0–D17 before LDCK↑	5		5		5		ns
		$\overline{PEN}$ before LDCK↑	5		5		5		
		LDCK inactive before $\overline{RESET}$ high	5		6		6		
t_h	Hold time	D0–D17 after LDCK↑	0		0		0		ns
		LDCK inactive after $\overline{RESET}$ high	5		6		6		
		$\overline{PEN}$ low after LDCK↑	3		3		3		
		$\overline{PEN}$ high after LDCK↓	0		0		0		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C$_L$ = 50 pF (unless otherwise noted) (see Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	'ACT7814-20			'ACT7814-25		'ACT7814-40		UNIT
			MIN	TYP[†]	MAX	MIN	MAX	MIN	MAX	
f_{max}	LDCK or UNCK		50			40		25		MHz
t_{pd}	LDCK↑	Any Q	9		20	9	22	9	24	ns
	UNCK↑		6	11.5	15	6	18	6	20	
t_{pd}[‡]	UNCK↑	Any Q		10.5						ns
t_{PLH}	LDCK↑	$\overline{EMPTY}$	6		15	6	17	6	19	ns
t_{PHL}	UNCK↑	$\overline{EMPTY}$	6		15	6	17	6	19	ns
	$\overline{RESET}$ low		4		16	4	18	4	20	
	LDCK↑	$\overline{FULL}$	6		15	6	17	6	19	
t_{PLH}	UNCK↑	$\overline{FULL}$	6		15	6	17	6	19	ns
	$\overline{RESET}$ low		4		18	4	20	4	22	
t_{pd}	LDCK↑	AF/AE	7		18	7	20	7	22	ns
	UNCK↑		7		18	7	20	7	22	
t_{PLH}	$\overline{RESET}$ low	AF/AE	2		10	2	12	2	14	ns
	LDCK↑	HF	5		18	5	20	5	22	
t_{PHL}	UNCK↑	HF	7		18	7	20	7	22	ns
	$\overline{RESET}$ low		3		12	3	14	3	16	
t_{en}	$\overline{OE}$	Any Q	2		9	2	10	2	11	ns
t_{dis}	$\overline{OE}$	Any Q	2		10	2	11	2	12	ns

† All typical values are at V$_{CC}$ = 5 V, T$_A$ = 25°C.
‡ This parameter is measured at C$_L$ = 30 pF (see Figure 4).

operating characteristics, V$_{CC}$ = 5 V, T$_A$ = 25°C

PARAMETER		TEST CONDITIONS		TYP	UNIT
C_{pd}	Power dissipation capacitance per FIFO channel	Outputs enabled	C$_L$ = 50 pF, f = 5 MHz	53	pF

PARAMETER MEASUREMENT INFORMATION

LOAD CIRCUIT

PARAMETER		S1
t_{en}	t_{PZH}	Open
	t_{PZL}	Closed
t_{dis}	t_{PHZ}	Open
	t_{PLZ}	Closed
t_{pd}	t_{PLH}	Open
	t_{PHL}	Open

VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES

VOLTAGE WAVEFORMS
PULSE DURATION

VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES

VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
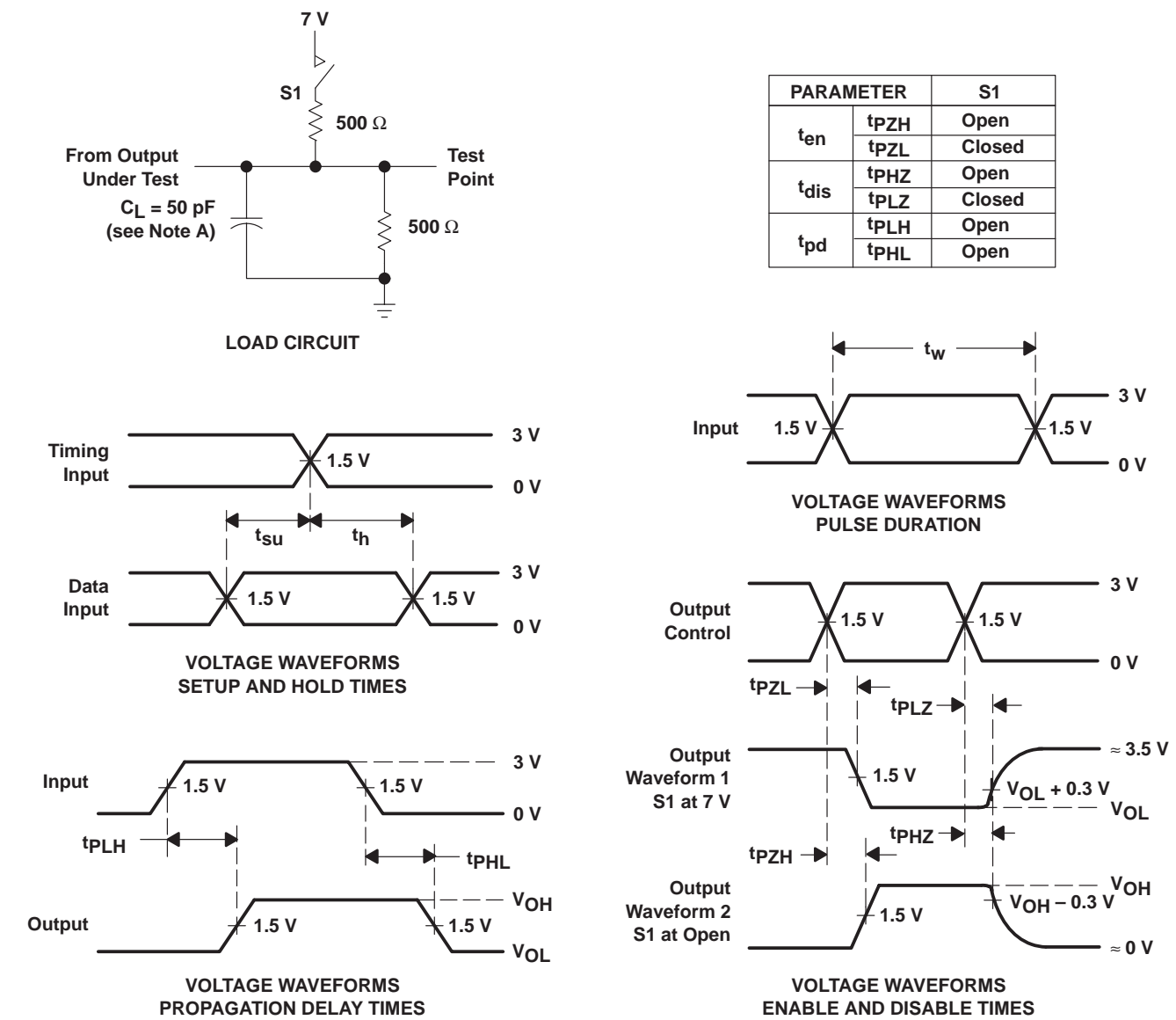
NOTE A: C_L includes probe and jig capacitance.

Figure 3. Load Circuit and Voltage Waveforms

TYPICAL CHARACTERISTICS
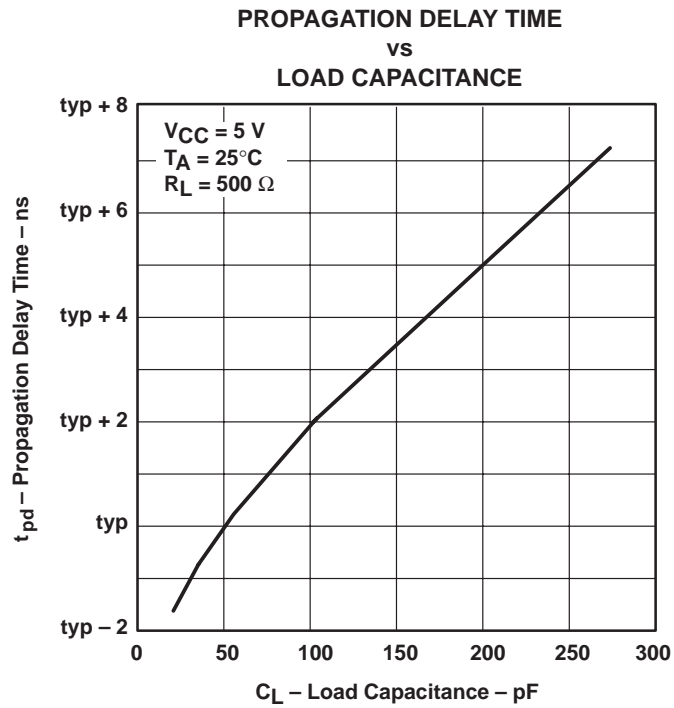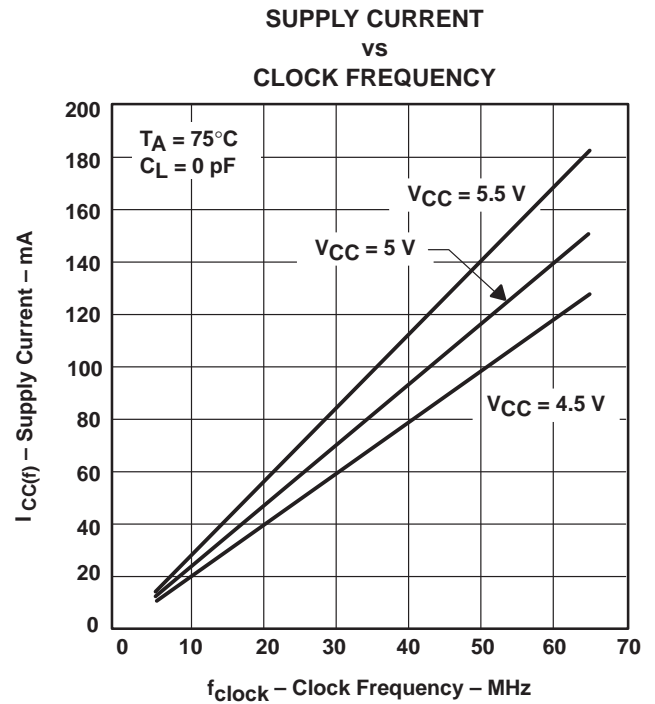
PROPAGATION DELAY TIME
vs
LOAD CAPACITANCE

$V_{CC} = 5\ V$
$T_A = 25°C$
$R_L = 500\ \Omega$

t_{pd} – Propagation Delay Time – ns

C_L – Load Capacitance – pF

Figure 4

SUPPLY CURRENT
vs
CLOCK FREQUENCY

$T_A = 75°C$
$C_L = 0\ pF$

$V_{CC} = 5.5\ V$
$V_{CC} = 5\ V$
$V_{CC} = 4.5\ V$

$I_{CC(f)}$ – Supply Current – mA

f_{clock} – Clock Frequency – MHz

Figure 5

APPLICATION INFORMATION

Figure 6. Word-Width Expansion: 64 × 36 Bits

![Texas Instruments logo](TI logo)

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74ACT7814-20DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT7814-20	Samples
SN74ACT7814-40DL	ACTIVE	SSOP	DL	56	20	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	ACT7814-40	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DL (R−PDSO−G56)   PLASTIC SMALL−OUTLINE PACKAGE

0.025 (0,635)

$\frac{0.0135\ (0,343)}{0.008\ (0,203)}$ ⊕ 0.005 (0,13) Ⓜ

56   29

$\frac{0.420\ (10,67)}{0.395\ (10,03)}$

$\frac{0.010\ (0,25)}{0.005\ (0,13)}$

$\frac{0.299\ (7,59)}{0.291\ (7,39)}$

Gage Plane

0.010 (0,25)

0°−8°

1   28

$\frac{0.730\ (18,54)}{0.720\ (18,29)}$

$\frac{0.040\ (1,02)}{0.020\ (0,51)}$

Seating Plane

0.110 (2,79) MAX   0.008 (0,20) MIN

⬠ 0.004 (0,10)

4040048−4/F   05/13

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
         D.   Falls within JEDEC MO−118

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